SY5842

Single Stage Flyback And PFC Controller With Primary Side Control For LED Lighting

General Description

The SY5842 is a single stage Flyback and PFC controller targeting at LED lighting applications. It is a primary side controller without applying any secondary feedback circuit for low cost, and drives the Flyback converter in the quasi-resonant mode to achieve higher efficiency. It integrates PFC compensating circuit to achieve high power factor and low THD while keeping accurate constant current. It adopts special design to achieve quick start up and reliable protection for safety requirement.

Features

- High PF>0.9, Low THD<10%
- Primary Side Control Eliminates the Opto-coupler.
- Valley Turn-on of the Primary MOSFET to Achieve Low Switching Losses
- Input Over/Under Voltage Protection
- Programmable Thermal Fold-back Function
- Reliable Short LED and Open LED Protection
- Quick Start up <500ms
- Low Start up Current:34μA Typical
- Package: SO8

Ordering Information

SY5842 □(□□□)

Package Code

Optional Spec Code

Ordering Number	Package type	Note
SY5842FAC	SO8	----

Applications

- LED Lighting

Typical Applications

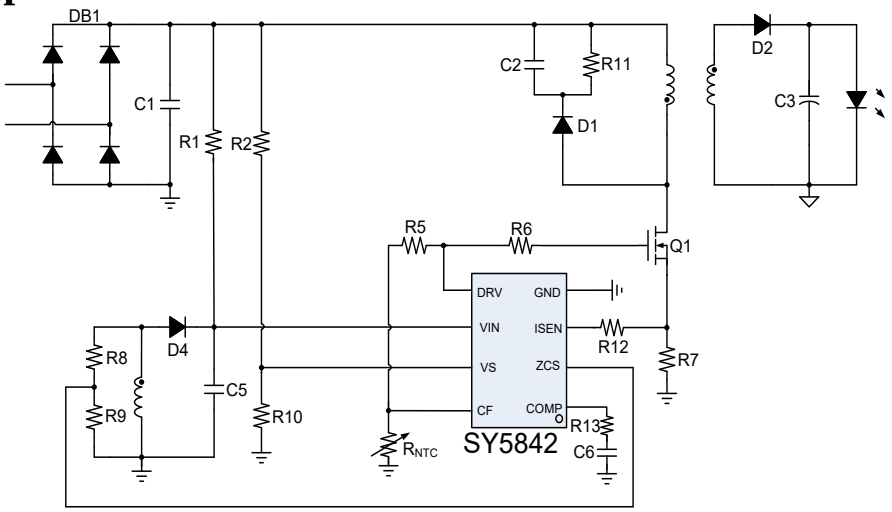
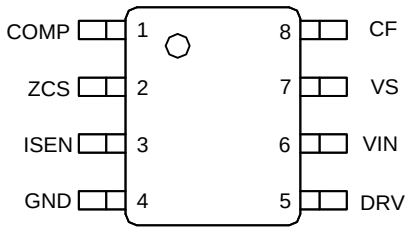


Figure 1. Schematic Diagram SO8

Pinout (top view)



(SO8)

Top Mark: DQQ*xyz* (device code: DQQ, ***x=year code, y=week code, z= lot number code***)

Pin Name	Pin Number	Pin Description
COMP	1	Loop compensation pin. Connect a RC network across this pin and ground to stabilize the control loop.
ZCS	2	Inductor current zero-crossing detection pin. This pin receives the auxiliary winding voltage by a resister divider and detects the inductor current zero crossing point. This pin also provides over voltage protection, line regulation modification and THD modification function simultaneously. If the voltage on this pin is above $V_{ZCS,OVP}$, the IC would enter over voltage protection mode. Good line regulation and THD performance can be achieved by adjusting the upper resistor of the divider.
ISEN	3	Current sense pin. Connect this pin to the source of the primary switch. Connect the sense resistor across the source of the primary switch and the GND pin. (current sense resister R_S: $R_S = k\frac{V_{REF} \times N_{PS}}{I_{OUT}}$, k=0.167) Also this pin used to detect transformer and secondary is short or not.
GND	4	Ground pin
DRV	5	Gate driver pin. Connect this pin to the gate of primary MOSFET.
VIN	6	Power supply pin. This pin also provides output over voltage protection along with ZCS pin.
VS	7	Input voltage sensing pin, connecting a resistor divider to line voltage.
CF	8	Internal reference setting pin.

Block Diagram

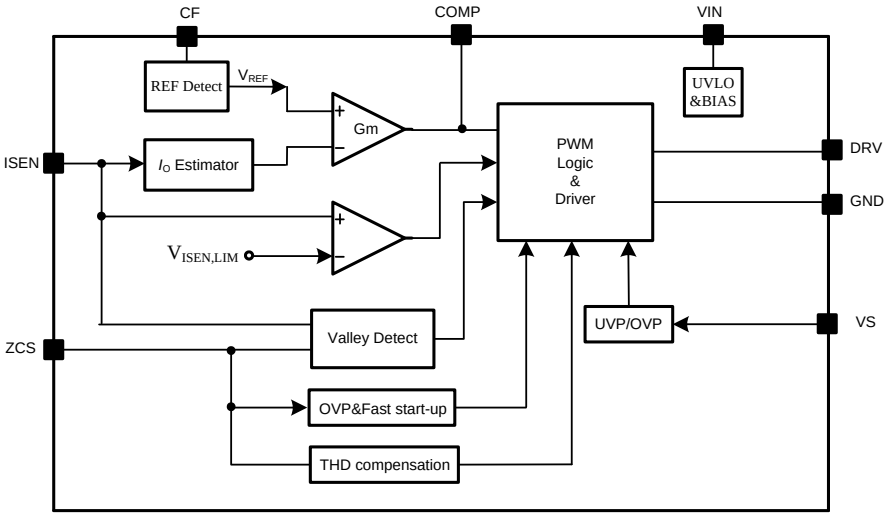


Figure2. Block Diagram

Absolute Maximum Ratings (Note 1)

VIN, DRV ---------- -0.3V~26V
Supply Current I_{VIN} ---------- 7mA
CF---------- -0.3V ~23V
ZCS----------0.3V ~3V
VS---------- -0.3V ~15V
ISEN, COMP ---------- -0.3~3.6V
Power Dissipation, @ T_A = 25°C SO8 ----------1.1W
Package Thermal Resistance (Note 2)
SO8, θJA ---------- 88°C/W
SO8, θJC ---------- 45°C/W
Junction Temperature Range ---------- -40°C to 150°C
Lead Temperature (Soldering, 10 sec.) ---------- 260°C
Storage Temperature Range ---------- -65°C to 150°C

Recommended Operating Conditions (Note 3)

VIN, DRV ---------- 8.5V~20V
Junction Temperature Range ---------- -40°C to 125°C

Electrical Characteristics

(V_{IN} = 12V (Note 3), T_A = 25°C unless otherwise specified)

Parameter	Symbol	Description	Min	Typ	Max	Unit
Power supply Section						
VIN Turn-on Threshold	V_{VIN_ON}		19	21	23	V
VIN Turn-off Threshold	V_{VIN_OFF}		6.7	7.3	8	V
VIN OVP Voltage	V_{VIN_OVP}			V_{VIN_ON}+4		V
Startup Current	I_{ST}	V_{VIN}<V_{VIN_ON}	24	34	46	μA
Discharge Current in OVP Mode	I_{VIN_OVP}	V_{VIN}=12V after OVP	5	7	10	mA
Error Amplifier Section						
Internal Reference High Clamp	V_{REF_H}	V_{CF}>1.35V	294	300	306	mV
Current Sense Section						
Current Limit Voltage	V_{ISEN_LIMIT}		0.4	0.45	0.5	V
Protection Limit for TR Short	V_{ISEN_EX}		0.8	0.9	1	V
ZCS Section						
ZCS Pin OVP Voltage Threshold	V_{ZCS_OVP}		1.43	1.5	1.57	V
Gate Driver Section						
Gate Driver Voltage	V_{GATE}	V_{VIN}>V_{GATE}	10.5	11.8	13	V
Maximum Source Current	I_{SOURCE}		140	200	260	mA
Minimum Sink Current	I_{SINK}		500	600	800	mA
Min ON Time	T_{ON_MIN}	V_{COMP}=2.7		450		ns
Max ON Time	T_{ON_MAX}		10	15	20	μs
Max OFF Time	T_{OFF_MAX}		42	60	79	μs
Min OFF Time	T_{OFF_MIN}		1.25	1.8	2.35	μs
Maximum Switching Frequency	F_{MAX}		96	120	176	kHz
VS Section						
VS Pin OVP Voltage Threshold	V_{VS_OVP}		1.47	1.5	1.53	V
VS Pin OVP Recover Voltage	$V_{VS\_OVP\_R}$			V_{VS_OVP}-0.05		V
VS Pin UVP Voltage Threshold	V_{VS_UVP}		0.35	0.4	0.45	V
VS Pin UVP Recover Voltage	$V_{VS\_UVP\_R}$			V_{VS_UVP}+0.03		V
VS Pin Discharge Current	I_{VS}	V_{VS}>1.2V,HYS=0.5V	13	18	24	μA
VS Pin Detect Time	T_{VS_DET}			23		mS
Thermal Section						
Thermal Fold-back Temperature	T_{FB}			150		°C
Thermal Shutdown Temperature	T_{SD}			160		°C

Note 1: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: Θ_{JA} is measured in the natural convection at T_A = 25°C on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2" x 2" FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

Note 3: Increase VIN pin voltage gradually higher than $V_{VIN,ON}$ voltage then turn down to 12V.

Operation

The SY5842 is a single stage Flyback and PFC controller targeting at LED lighting applications.

SY5842 provides primary side control to eliminate the opto-couplers and the secondary feedback circuits, which can decrease the BOM cost of the system design.

High power factor is achieved by internal PFC compensating circuit, with which both the control scheme and the circuit structure are simple.

In order to reduce the switching loss and improve EMI performance, Quasi-Resonant switching mode is applied. The maximum switching frequency is limited at 120 KHz to reduce switching losses and improve EMI performance when the converter is operated at light load condition.

SY5842 provides thermal foldback function by CF pin.

SY5842 provides reliable protections such as Input over/under voltage protection, Short Circuit Protection (SCP), Open LED Protection (OLP), Over Temperature Protection (OTP), transformer shorted protection and power diode short protection, etc.

SY5842 is available with SO8 package.

Applications Information

Start up

After AC supply or DC BUS is powered on, the capacitor C_{VIN} between VIN and GND pin is charged up by BUS voltage through a start up resistor R_{ST}. Once V_{VIN} rises up to V_{VIN_ON}, the internal blocks start to work. V_{VIN} will be pulled down by internal consumption of IC until the auxiliary winding of transformer could supply enough energy to maintain V_{VIN} above V_{VIN_OFF}.

The whole start up procedure is divided into two sections shown in Fig.3. t_{STC} is the C_{VIN} charged up section, and t_{STO} is the output voltage build-up section. The start-up time t_{ST} is composed of t_{STC} and t_{STO}, and usually t_{STO} is much smaller than t_{STC}.

t_{STO} is fast start-up stage, which will help to create output voltage quickly. After t_{STO}, IC works in constant current mode.

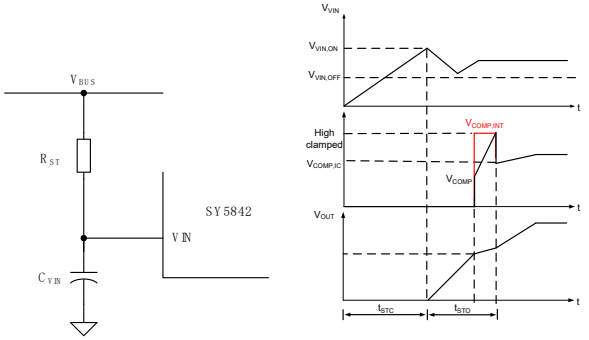


Fig.3 Start up

The start up resistor R_{ST} and C_{VIN} are designed by rules as below:

(a) Preset start-up resistor R_{ST}, make sure that the current through R_{ST} is larger than I_{ST} and smaller than 1mA.

$$\frac{V_{BUS}}{1mA} < R_{ST} < \frac{V_{BUS}}{I_{ST}} \quad (1)$$

Where V_{BUS} is the BUS line voltage.

(b) Select C_{VIN} to obtain an ideal start up time $t_{ST,}$ and ensure the output voltage is built up at one time.

$$C_{VIN} = \frac{(\frac{V_{BUS}}{R_{ST}} - I_{ST}) \times t_{ST}}{V_{VIN\_ON}} \quad (2)$$

(c) If the C_{VIN} is not big enough to build up the output voltage at one time. Increase C_{VIN} and decrease R_{ST}, go back to step (a) and redo such design flow until the ideal start up procedure is obtained.

Internal pre-charge design for quick start up

In t_{STO1}, V_{ZCS} is lower than certain threshold $V_{ZCS,ST}$(0.55V), which means the output voltage is not built up, during this time, peak current mode is adopted to reduce start up time shown in Fig.4.

In t_{STO2}, V_{COMP} is pre-charged by internal current source until it is over the initial voltage V_{COMP_IC}. V_{COMP_IC} can be programmed by R_{COMP}.

The voltage pre-charged V_{COMP_IC} in start-up procedure can be programmed by $R_{COMP:}$

$$V_{COMP\_IC} = 2.0V - 180\mu A \times R_{COMP} \quad (3)$$

Where V_{COMP_IC} is the pre-charged voltage of COMP pin.

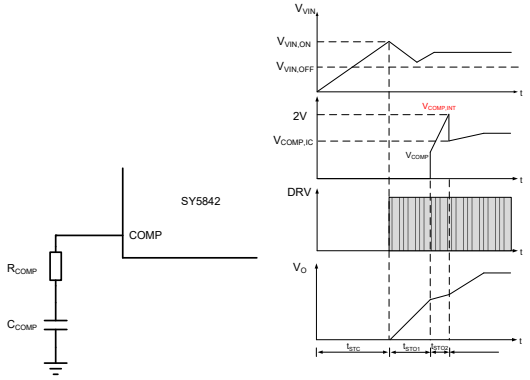


Fig.4 Pre-charge scheme in start up

Generally, a big capacitance of C_{COMP} is necessary to achieve high power factor and stabilize the system loop (1μF~4.7μF is recommended).

The voltage pre-charged in start-up procedure can be programmed by R_{COMP}; On the other hand, larger R_{COMP} can provide larger phase margin for the control loop.

Shut down

After AC supply or DC BUS is powered off, the energy stored in the BUS capacitor will be discharged. When the auxiliary winding of the transformer cannot supply enough energy to VIN pin, V_{VIN} will drop down. Once V_{VIN} is below V_{VIN_OFF}, the IC will stop working and V_{COMP} will be discharged to zero.

Primary side constant current control

Primary side control is applied to eliminate secondary feedback circuit and opto-coupler, which reduces the BOM cost. The switching waveforms are shown in Fig.5.

The output current I_{OUT} can be represented by

$$I_{OUT}=\frac{I_{SP}}{2}\times\frac{t_{DIS}}{t_S} \quad (4)$$

Where I_{SP} is the peak current of the secondary side; t_{DIS} is the discharge time of the transformer; t_S is the switching period.

The secondary peak current is related with primary peak current, if the effect of the leakage inductor is neglected.

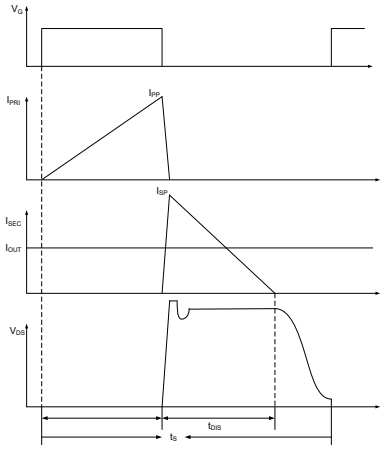


Fig.5 switching waveforms

$$I_{SP}=N_{PS}\times I_{PP} \quad (5)$$

Where N_{PS} is the turn ratio of primary to secondary of the transformer.

Thus, I_{OUT} can be represented by

$$I_{OUT}=\frac{N_{PS}\times I_{PP}}{2}\times\frac{t_{DIS}}{t_S} \quad (6)$$

The primary peak current I_{PP} and inductor current discharge time t_{DIS} can be detected by ISEN and ZCS pin, which is shown in Fig.6.These signals are processed and applied to the negative input of the gain modulator. In static state, the positive and negative inputs are equal.

$$V_{REF}=I_{PP}\times R_S\times\frac{t_{DIS}}{t_S}\times k_1 \quad (7)$$

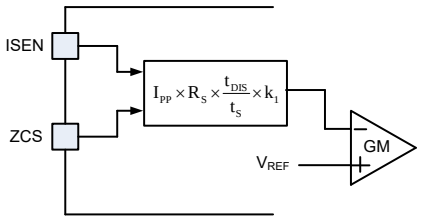


Fig.6 Output current detection diagram

Finally, the output current I_{OUT} can be represented by

$$I_{OUT}=\frac{V_{REF}\times N_{PS}}{R_S\times 2\times k_1} \quad (8)$$

Where k_1(3) is the output current weight coefficient; V_{REF} is the internal reference voltage; R_S is the current sense resistor.

k_1 and V_{REF} are all internal constant parameters, I_{OUT} can be programmed by N_{PS} and R_S.

$$R_S = \frac{V_{REF} \times N_{PS}}{I_{OUT} \times 2 \times k_1} \quad (9)$$

Then,

$$R_S = \frac{k \times V_{REF} \times N_{PS}}{I_{OUT}}, k = \frac{1}{2k_1} \quad (10)$$

Quasi-Resonant Operation

QR mode operation provides low turn-on switching losses for the converter.

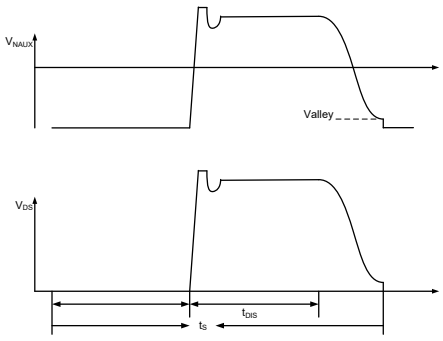


Fig.7 QR mode operation

The voltage across drain and source of the primary MOSFET is reflected by the auxiliary winding of the Flyback transformer. ZCS pin detects the voltage across the auxiliary winding by a resistor divider. When the voltage across drain and source of the primary MOSFET is at voltage valley, the MOSFET would be turned on.

Internal THD Compensation

The IC provides THD compensation function by adjusting the ZCS upper resistor.

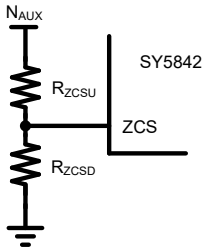


Fig.8 Internal THD Compensation

Normally, R_{ZCSU} can be selected by

$$R_{ZCSU} = \frac{N_{AUX} \times V_{OUT}}{N_S \times 80uA} \quad (11)$$

Where R_{ZCSU} is the upper resistor of the divider; N_S and N_{AUX} are the turns of secondary winding and auxiliary winding separately.

Line regulation modification

The IC provides line regulation improvement function by adjusting the external resistor.

Due to the sample delay of ISEN pin and other internal delay, the output current increases with the increasing of input BUS line voltage. A small compensation voltage ΔV_{ISEN_C} is added to ISEN pin during ON time to improve such performance. This ΔV_{ISEN_C} is adjusted by the upper resistor of the divider connected to ZCS pin and external resistor R_{ISEN_C} on ISEN pin.

$$\Delta V_{ISEN,C} = V_{BUS} \times \frac{N_{AUX}}{N_P} \times \frac{1}{R_{ZCSU}} \times k_2 \times (R_{k2} + R_{ISEN,C}) \quad (12)$$

Where R_{ZCSU} is the upper resistor of the divider; $k_2(0.1)$ is an internal constant as the modification coefficient; $R_{k2}(340\Omega)$ is an internal feed-forward resistor; auxiliary resistor $R_{ISEN,C}$ can be added to enhance feed-forward effects.

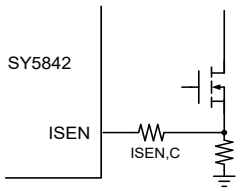


Fig.9 Feed-forward resistor

The compensation is mainly related with R_{ZCSU}, larger compensation is achieved with smaller R_{ZCSU}. The line regulation can be modified by adjusting R_{ZCSU} and R_{ISEN_C}.

Over Voltage Protection (OVP) & Open LED Protection (OLP)

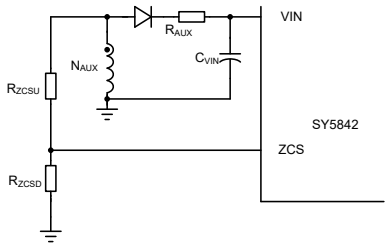


Fig.10 OVP&OLP

The output voltage is reflected by the auxiliary winding voltage of the Flyback transformer, and both ZCS pin and VIN pin provide over voltage protection function. When the load is null or large transient happens, the output voltage will exceed the rated value. When V_{VIN} exceeds V_{VIN_OVP} or V_{ZCS} exceeds V_{ZCS_OVP}, the over voltage protection is triggered and the IC will discharge V_{VIN} by an internal current source. Once V_{VIN} is below V_{VIN_OFF}, the IC will shut down and be charged again by BUS voltage through start up resistor. If the over voltage condition still exists, the system will operate in hiccup mode.

Thus, the turns of the auxiliary winding N_{AUX} and the resistor divider is related with the OVP function.

$$\frac{V_{ZCS,OVP}}{V_{OVP}} = \frac{N_{AUX}}{N_S} \times \frac{R_{ZCSD}}{R_{ZCSU}+R_{ZCSD}} \quad (13)$$

$$\frac{V_{VIN,OVP}}{V_{OVP}} \geq \frac{N_{AUX}}{N_S} \quad (14)$$

Where V_{OVP} is the output over voltage specification; R_{ZCSU} and R_{ZCSD} compose the resistor divider. The turn ratio of N_S to N_{AUX} and the ratio of R_{ZCSU} to R_{ZCSD} could be induced from equation (15) and (16).

So R_{ZCSD} can be selected by

$$R_{ZCSD} = \frac{\frac{V_{ZCS,OVP}}{V_{OVP}} \times \frac{N_S}{N_{AUX}}}{1-\frac{V_{ZCS,OVP}}{V_{OVP}} \times \frac{N_S}{N_{AUX}}} \times R_{ZCSU} \quad (16)$$

Where V_{OVP} is the output over voltage protection specification; V_{OUT} is the rated output voltage; R_{ZCSU} and R_{ZCSD} is the resistor of the divider; N_S and N_{AUX} are the turns of secondary winding and auxiliary winding separately.

Short Circuit Protection (SCP)

When the output is shorted to ground, the output voltage is clamped to zero. The voltage of the auxiliary winding is proportional to the output winding, so valley signal cannot be detected by ZCS pin. Without valley detection, MOSFET cannot be turned ON until maximum off time t_{OFF_MAX} is matched. If MOSFET is turned ON by t_{OFF_MAX} 64 times continuously, IC will be shut down and enter into hiccup mode.

If the output voltage is not low enough to disable valley detection in short condition, V_{VIN} will drop down without auxiliary winding supply. Once V_{VIN} is below V_{VIN_OFF}, the IC will shut down and be charged again by the BUS voltage through the start-up resistor. If the short circuit condition still exists, the system will operate in hiccup mode.

In order to guarantee SCP function is not effected by voltage spike of auxiliary winding, a filter resistor R_{AUX} is needed (10Ω typically) shown in Fig.8.

Input Under/Over Voltage Protection

The input voltage is reflected by R_{VSU} and R_{VSD} divider, the VS pin provide both input under voltage protection and input over voltage protection function.

During the system operating, the input under voltage protection will be triggered if the VS voltage is lower than V_{VS_UVP} for a continuous time of T_{VS_DET}. Then, the system will not output PWM signal, V_{VIN} will be discharged to UVLO naturally and system will restart. Once V_{VS} exceeds V_{VS_UVPR}, the system will resume normal operation. Otherwise the system will operate in hiccup mode.

During the system operating, the input over voltage protection will be triggered if the VS voltage exceeds V_{VS_OVP}. Then, the system will not output PWM signal, V_{VIN} will be discharged to UVLO naturally and system will restart. Once V_{VS} is lower than V_{VS_OVPR} for a continuous time of T_{VS_DET}, the system will resume normal operation. Otherwise the system will operate in hiccup mode.

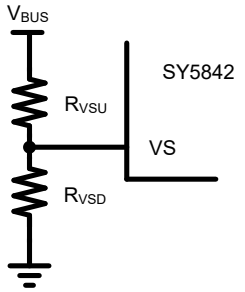


Fig.11 Input Under/Over Voltage Protection

Input UVP/OVP can be adjusted separately by,

$$V_{IN,UVP} = 0.707 \times \frac{R_{VSU}+R_{VSD}}{R_{VSD}} \times V_{VS,UVP} \quad (16)$$

$$V_{IN,OVP} = 0.707 \times \frac{R_{VSU}+R_{VSD}}{R_{VSD}} \times V_{VS,OVP} + 18uA \times R_{VSU} \quad (17)$$

$$V_{IN,UVPR} = 0.707 \times \frac{R_{VSU} + R_{VSD}}{R_{VSD}} \times V_{VS,UVPR} \quad (18)$$

$$V_{IN,OVPR} = 0.707 \times \frac{R_{VSU} + R_{VSD}}{R_{VSD}} \times V_{VS,OVPR} + 18uA \times R_{VSU} \quad (19)$$

Where V_{IN_UVP} and V_{IN_OVP} is the input under/over voltage specification; V_{IN_UVPR} and V_{IN_OVPR} is the input under/over recovery voltage specification; R_{VSU} and R_{VSD} compose the resistor divider. V_{VS_UVP} and V_{VS_OVP} is UVP/OVP voltage threshold; V_{VS_UVPR} and V_{VS_OVRP} is UVP/OVP recovery voltage threshold.

Thermal Foldback Protection

The current reference is feedback by CF.

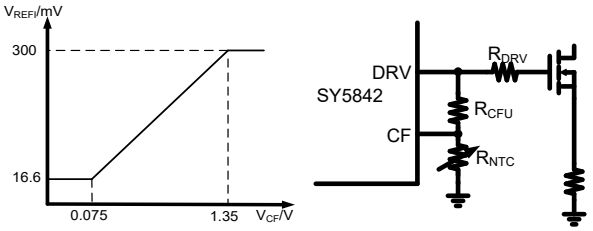


Fig.12 Thermal Foldback

As showed above, if V_{CF} is lower than 75mV, the output current is maintained at 5.5 percent of the full load output current; When V_{CF} is higher than 1.35V, the output current is 100 percent of full load output current; The available Thermal Foldback range of V_{CF} is from 75mV to 1.35V.
When V_{VIN}>12V, V_{DRV} is high clamp to 12V, so CF pin can obtain current reference by R_{NTC} and R_{CFU} divider from DRV.

R_{NTC} can be selected by T_{FB} curve. And R_{CFU} is selected by

$$R_{CFU} = \frac{12V \times R_{NTC}(@T_{FB})}{1.35V} - R_{NTC}(@T_{FB}) \quad (20)$$

Where $R_{NTC}(@T_{FB})$ is the resistance of NTC resistor when protection acts.

Power Device Design

MOSFET and Diode

When the operation condition is with maximum input voltage and full load, the voltage stress of MOSFET and secondary power diode is maximized;

$$V_{MOS\_DS\_MAX} = \sqrt{2}V_{AC\_MAX} + N_{PS} \times (V_{OUT} + V_{D\_F}) + \Delta V_S \quad (21)$$

$$V_{D\_R\_MAX} = \frac{\sqrt{2}V_{AC\_MAX}}{N_{PS}} + V_{OUT} \quad (22)$$

Where V_{AC_MAX} is the maximum input AC RMS voltage; N_{PS} is the turn ratio of the Flyback transformer; V_{OUT} is the rated output voltage; V_{D_F} is the forward voltage of secondary power diode; ΔV_S is the overshoot voltage clamped by RCD snubber during OFF time.

When the operation condition is with minimum input voltage and full load, the current stress of MOSFET and power diode is maximized.

$$I_{MOS\_PK\_MAX} = I_{P\_PK\_MAX} \quad (23)$$

$$I_{MOS\_RMS\_MAX} = I_{P\_RMS\_MAX} \quad (24)$$

$$I_{D\_PK\_MAX} = N_{PS} \times I_{P\_PK\_MAX} \quad (25)$$

$$I_{D\_AVG} = I_{OUT} \quad (26)$$

Where $I_{P\_PK\_MAX}$ and $I_{P\_RMS\_MAX}$ are maximum primary peak current and RMS current, which will be introduced later.

Transformer (N_{PS} and L_M)

N_{PS} is limited by the electrical stress of the power MOSFET:

$$N_{PS} \le \frac{V_{MOS\_(BR)DS} \times 90\% - \sqrt{2}V_{AC\_MAX} - \Delta V_S}{V_{OUT} + V_{D\_F}} \quad (27)$$

Where $V_{MOS\_(BR)DS}$ is the breakdown voltage of the power MOSFET.

In Quasi-Resonant mode, each switching period cycle t_S consists of three parts: current rising time t_1, current falling time t_2 and quasi-resonant time t_3 are shown as Fig.13.

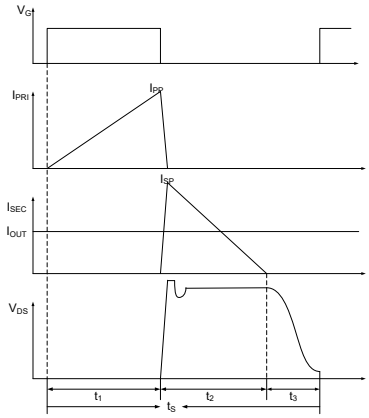


Fig.13 switching waveforms

The ON time increases with the decreasing of input AC RMS voltage and the increasing of load. When the operation condition is with minimum input AC RMS voltage and full load, the ON time is maximized. On the other hand, when the input voltage is at the peak value, the OFF time is maximized. Thus, the minimum switching frequency f_{S_MIN} happens at the peak value of input voltage with minimum input AC RMS voltage and maximum load condition; meanwhile, the maximum peak current through MOSFET and the transformer happens.

Once the minimum frequency f_{S_MIN} is set, the inductance of the transformer could be induced. The design flow is shown as below:

(a) Select N_{PS}

$$N_{PS} \le \frac{V_{MOS\_(BR)DS} \times 90\% - \sqrt{2}V_{AC\_MAX} - \Delta V_S}{V_{OUT} + V_{D\_F}} \quad (28)$$

(b) Preset minimum frequency f_{S_MIN}

(c) Compute relative t_S, t_1 (t_3 is omitted to simplify the design here)

$$t_S = \frac{1}{f_{S\_MIN}} \quad (29)$$

$$t_1 = \frac{t_S \times N_{PS} \times (V_{OUT} + V_{D\_F})}{\sqrt{2}V_{AC\_MIN} + N_{PS} \times (V_{OUT} + V_{D\_F})} \quad (30)$$

(d) Design inductance L_M

$$L_M = \frac{V_{AC\_MIN}^2 \times t_1^2 \times \eta}{2P_{OUT} \times t_S} \quad (31)$$

(e) Compute t_3

$$t_3 = \pi \times \sqrt{L_M \times C_{Drain}} \quad (32)$$

Where C_{Drain} is the parasitic capacitance at drain of MOSFET.

(f) Compute primary maximum peak current $I_{P\_PK\_MAX}$ and RMS current $I_{P\_RMS\_MAX}$ for the transformer fabrication.

$$I_{P\_PK\_MAX} = \frac{2P_{OUT} \times [\frac{L_M}{\sqrt{2}V_{AC\_MIN}} + \frac{L_M}{N_{PS} \times (V_{OUT} + V_{D\_F})}]}{L_M \times \eta} + \frac{\sqrt{4P_{OUT}^2 \times [\frac{L_M}{\sqrt{2}V_{AC\_MIN}} + \frac{L_M}{N_{PS} \times (V_{OUT} + V_{D\_F})}]^2 + 4L_M \times \eta \times P_{OUT} \times t_3}}{L_M \times \eta} \quad (33)$$

Where η is the efficiency; P_{OUT} is rated full load power

Adjust t_1 and t_S to t_1' and t_S' considering the effect of t_3

$$t_S' = \frac{\eta \times L_M \times I_{P\_PK\_MAX}^2}{4P_{OUT}} \quad (34)$$

$$t_1' = \frac{L_M \times I_{P\_PK\_MAX}}{\sqrt{2}V_{AC\_MIN}} \quad (35)$$

$$I_{P\_RMS\_MAX} \approx \sqrt{\frac{t_1'}{6t_S'}} \times I_{P\_PK\_MAX} \quad (36)$$

(g) Compute secondary maximum peak current $I_{S\_PK\_MAX}$ and RMS current $I_{S\_RMS\_MAX}$ for the transformer fabrication.

$$I_{S\_PK\_MAX} = N_{PS} \times I_{P\_PK\_MAX} \quad (37)$$

$$t_2' = t_S' - t_1' - t_3 \quad (38)$$

$$I_{S\_RMS\_MAX} \approx \sqrt{\frac{t_2'}{6t_S'}} \times I_{S\_PK\_MAX} \quad (39)$$

Transformer design (N_P, N_S, N_{AUX})

The design of the transformer is similar with ordinary Flyback transformer.The parameters below are necessary:

Necessary parameters	
Turns ratio	N_{PS}
Inductance	L_M
Primary maximum current	$I_{P\_PK\_MAX}$
Primary maximum RMS current	$I_{P\_RMS\_MAX}$
Secondary maximum RMS current	$I_{S\_RMS\_MAX}$

The design rules are as followed:

(a) Select the magnetic core style, identify the effective area Ae.

(b) Preset the maximum magnetic flux ΔB

ΔB=0.22~0.26T

(c) Compute primary turn N_P

$$N_P = \frac{L_M \times I_{P\_PK\_MAX}}{\Delta B \times A_e} \quad (40)$$

(d) Compute secondary turn N_S

$$N_S = \frac{N_P}{N_{PS}} \quad (41)$$

(e) Compute auxiliary turn N_{AUX}

$$N_{AUX} = N_S \times \frac{V_{VIN}}{V_{OUT}} \quad (42)$$

Where V_{VIN} is the working voltage of VIN pin (12V~15V is recommended).

(f) Select an appropriate wire diameter

With $I_{P\text{-}RMS\text{-}MAX}$ and $I_{S\text{-}RMS\text{-}MAX}$, select appropriate wire to make sure the current density ranges from 4A/mm^2 to 10A/mm^2.

(g) If the winding area of the core and bobbin is not enough, reselect the core style, go to **(a)** and redesign the transformer until the ideal transformer is achieved.

Output capacitor C_{OUT}

Preset the output current ripple ΔI_{OUT}, C_{OUT} is induced by

$$C_{OUT} = \frac{\sqrt{(\frac{2I_{OUT}}{\Delta I_{OUT}})^2 - 1}}{4\pi f_{AC} R_{LED}} \quad (43)$$

Where I_{OUT} is the rated output current; ΔI_{OUT} is the demanded current ripple; f_{AC} is the input AC supply frequency; R_{LED} is the equivalent series resistor of the LED load.

RCD snubber for MOSFET

The power loss of the snubber P_{RCD} is evaluated first

$$P_{RCD} = \frac{N_{PS} \times (V_{OUT} + V_{D\_F}) + \Delta V_S}{\Delta V_S} \times \frac{L_K}{L_M} \times P_{OUT} \quad (44)$$

Where N_{PS} is the turns ratio of the Flyback transformer; V_{OUT} is the output voltage; V_{D_F} is the forward voltage of the power diode; ΔV_S is the overshoot voltage clamped by RCD snubber; L_K is the leakage inductor; L_M is the inductance of the Flyback transformer; P_{OUT} is the output power.

The R_{RCD} is related with the power loss:

$$R_{RCD} = \frac{(N_{PS} \times (V_{OUT} + V_{D\_F}) + \Delta V_S)^2}{P_{RCD}} \quad (45)$$

The C_{RCD} is related with the voltage ripple of the snubber ΔV_{C_RCD}:

$$C_{RCD} = \frac{N_{PS} \times (V_{OUT} + V_{D\_F}) + \Delta V_S}{R_{RCD} f_S \Delta V_{C\_RCD}} \quad (46)$$

Layout

(a) To achieve better EMI performance and reduce line frequency ripples, the output of the bridge rectifier should be connected to the BUS line capacitor first, then to the switching circuit.

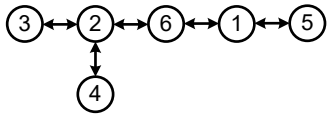
(b) The circuit loop of all switching circuit should be kept small: primary power loop, secondary loop and auxiliary power loop.

(c) Bias supply trace should be connected to the bias supply capacitor first instead of GND pin. The bias supply capacitor should be put beside the IC.

(d) Loop of 'Source pin – current sample resistor – GND pin' .should be kept as small as possible.

(e) The resistor divider is recommended to be put beside the IC.

(f) The connection of ground is recommended as:



Ground ①: ground of BUS line capacitor
Ground ②: ground of bias supply capacitor and GND pin

Ground ③: ground node of auxiliary winding
Ground ④: ground of signal trace except GND pin
Ground ⑤: primary ground node of Y capacitor.
Ground ⑥: ground of current sample resistor

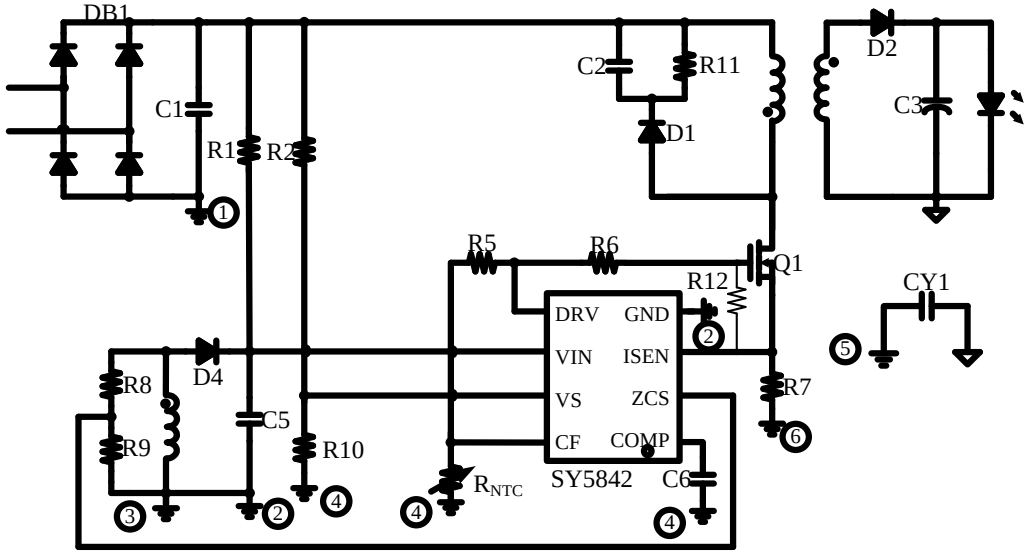
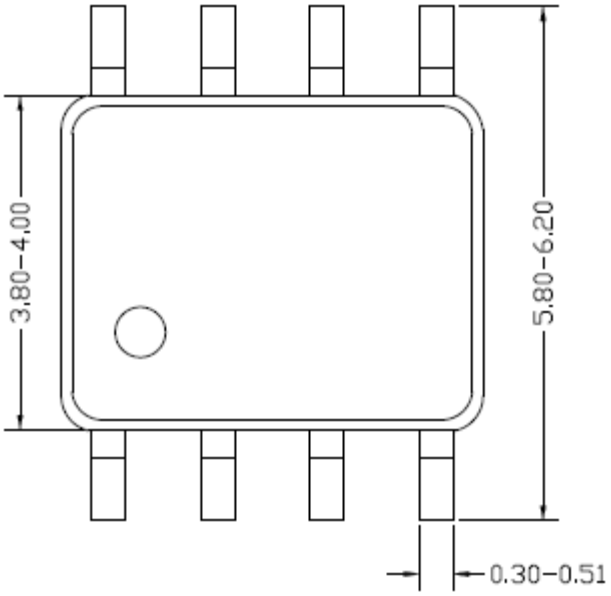
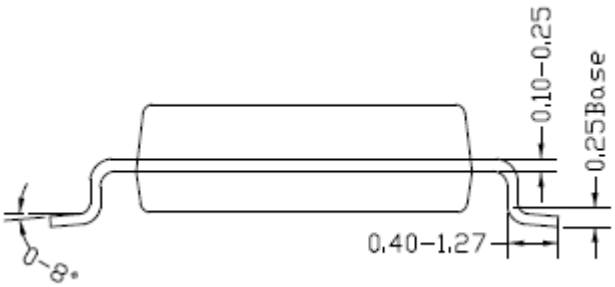


Fig.14 Ground Layout

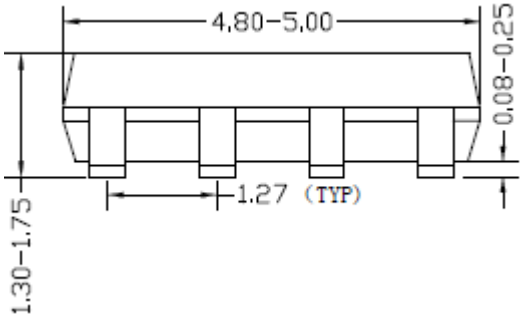
SO8 Package outline & PCB layout design



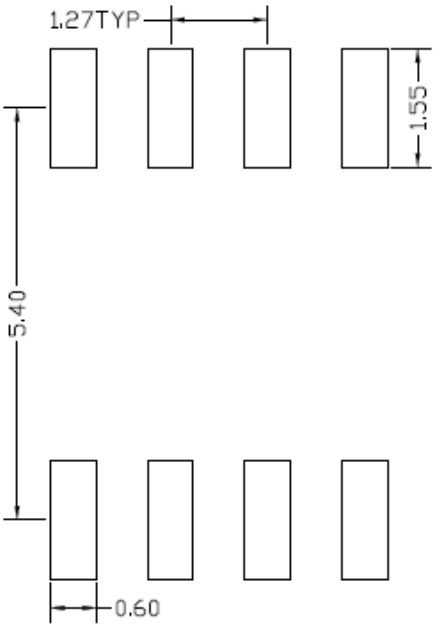
Top view



Side view



Front view

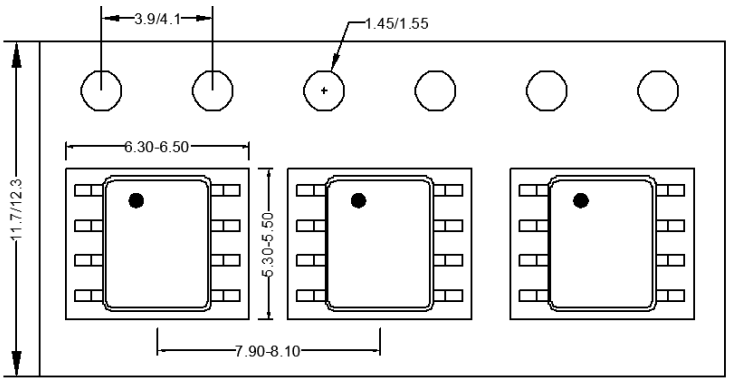


Recommended Pad Layout (Reference only)

Notes: **All dimension in millimeter and exclude mold flash & metal burr.**

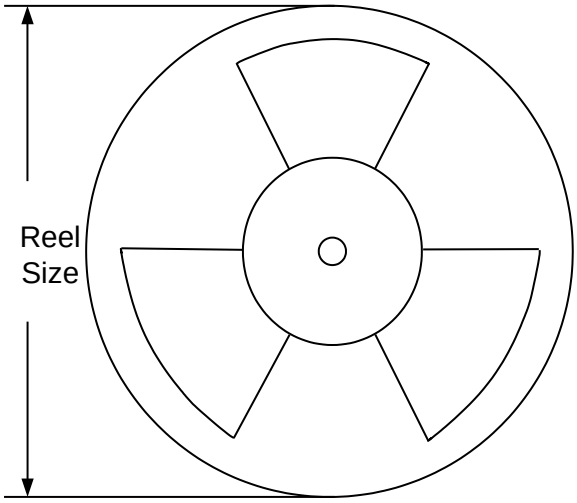
Taping & Reel Specification

1. Taping orientation for packages（SO8）



Feeding direction ⟶

2. Carrier Tape & Reel specification for packages



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SO8	12	8	13"	400	400	2500

Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

Date	Revision	Change
December 29,2021	Revision 0.9	Initial Risk Production Release
December 29,2022	Revision 1.0	Initial Production Release

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